



November 19, 2003

Dear Customer,

Aeroflex Colorado Springs (formerly Aeroflex UTMC) appreciates your interest and use of our products, specifically our family of RadHard MSI components. As we advised you in January, 2003, we are migrating selected product types of our RadHard MSI family to a new wafer fab. We are pleased to inform you that we have migrated ten (10) RadHard MSI to AMI Semiconductor, 0.6 $\mu$ m CMOS technology. Please reference Appendix A of this document for a list of migrated products.

Although the migrated RadHard MSI devices are form, fit, and functionally compatible to their predecessors, some product versions will be affected.

- 1Mrads(Si) versions of each device (tested per MIL-STD-883 Method 1019 Condition A) will no longer be offered under device type 01
- Dose rate testing will no longer be specified in the Standard Microcircuit Drawing (SMD)
- DIP package offerings will be discontinued for all device types
- For product offered in die form, the backside bias of the migrated RadHard MSI devices has changed from  $V_{DD}$  to  $V_{SS}$
- The backside bias change is denoted in the SMD as a change in the code from 9A to 9B

Following the release of the migrated RadHard MSI to their respective SMDs under device type 01, Aeroflex Colorado Springs will proceed to add two new device types to each SMD. These new device types will operate over a wider power supply range (3.0V to 5.5V). Device type 02 will be offered to 1Mrads(Si) per MIL-STD-883 Method 1019 Condition B testing. Device type 03 will satisfy 500krads(Si) and below per MIL-STD-883 Method 1019 Condition A.

Sales of our existing inventory for old components is "first come, first serve". Many have been depleted, but please contact your Aeroflex regional sales manager who has the remaining inventory.

If you have questions regarding any of the migrated RadHard MSI components, please contact your Aeroflex regional sales manager. If you have any additional questions, please contact me at (719) 594-8048, or email me at [tim.meade@aeroflex.com](mailto:tim.meade@aeroflex.com).

Regards,

A handwritten signature in cursive script that reads "Timothy L. Meade".

Timothy L. Meade  
Sr. Applications Engineer

## APPENDIX A

<b>Aeroflex Base Part #:</b>	<b>New PIC#:</b>	<b>SMD#:</b>	<b>SMD Release (Dev. Type 01)</b>	<b>Final SMD Release (Dev. Types 02 &amp; 03)</b>
UT54ACTS164	LA164	96557	Nov. 2003	Dec. 2003
UT54ACTS541	LA541	96595	Nov. 2003	Jan. 2004
UT54ACS132	CA132	96542	Nov. 2003	Jan. 2004
UT54ACS14	CA014	96524	Nov. 2003	Dec. 2003
UT54ACS109	CA109	96540	Nov. 2003	Jan. 2004
UT54ACTS08	LA008	96519	Dec. 2003	Jan. 2004
UT54ACS165	CA165	96558	Dec. 2003	Jan. 2004
UT54ACS02	CA002	96514	Dec. 2003	Jan. 2004
UT54ACTS153	LA153	96551	Dec. 2003	Jan. 2004
UT54ACS164	CA164	96556	Dec. 2003	Jan. 2004

Note: The Aeroflex base part number pertaining to product device types 02 and 03 will include the suffix "E". (e.g. UT54ACTS164E) This is to help customers differentiate the old and new versions of affected products when the devices are not purchased through an SMD.